

Title (en)  
DIAMOND BODY

Title (de)  
DIAMANTKÖRPER

Title (fr)  
CORPS DE DIAMANT

Publication  
**EP 0953208 A1 19991103 (DE)**

Application  
**EP 97953665 A 19971220**

Priority  
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Abstract (en)  
[origin: DE19701680A1] The invention concerns a diamond body designed to enable the thermal contacting with at least one source of heat (30) and presenting at least one recess (13, 15) defining an angular position in relation to the mechanical tensions generated by said or any source of heat (30). Consequently, the mechanical tensions generated at various temperatures, either, for example, by various thermal expansion coefficients of the diamond body (12) or by the source of heat (30) featured by one semi-conductor component, are at least partly compensated, resulting in the possibility to take advantage of the exceptional thermoconductive capacity and insulating characteristics of the diamond, including diamond bodies (12) of a relatively big size.

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**H01L 23/373**

IPC 8 full level  
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Citation (search report)  
See references of WO 9832171A1

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